

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (currently amended) A method for mounting through an adhesive sheet an electronic component on a printed circuit board provided with a wiring pattern said printed circuit board having bumps and said wiring pattern covering said bumps to form an uneven surface, the method comprising the steps of:  
placing the adhesive sheet on the wiring pattern so as to leave said uneven surface causing intervening air~~a space consists of a gap~~ between the adhesive sheet and the printed circuit board;  
heating the intervening air~~within the space intervening between~~ the adhesive sheet and the printed circuit board; and  
bonding, while heating the air, the adhesive sheet to cover an area of the printed circuit board to be mounted with the electronic component.
2. (previously presented) The method according to claim 1, wherein the air intervening between the adhesive sheet and the printed circuit board is heated upon heating the printed circuit board.
3. (previously presented) The method according to claim 2, wherein the electronic component is pressurized and bonded on to the adhesive sheet after the printed circuit board bonded with the adhesive sheet is cooled.

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4. (previously presented) The method for mounting the electronic component according to claim 1, wherein temperature of the heating process is set to a range between equal to or higher than 60 degrees Celsius and equal to or lower than a reaction temperature of the adhesive sheet.

5. (previously presented) The method for mounting the electronic component according to claim 1, wherein the adhesive sheet is made of an anisotropic conductive film.

6. (previously presented) The method for mounting the electronic component according to claim 1, wherein the printed circuit board is made of a flexible board.

7. (currently amended) The method of Claim 1, further including the step of adhering the electronic component with pressure on the adhesive sheet upon reducing an amount of interveningtrapped air.